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(71)Applicant : INTERNATL BUSINESS MACH  
CORP <IBM>

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(72)Inventor : LAUFFER JOHN M  
SCHUMACHER RICHARD A

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**(54) MULTI-LAYER CIRCUIT PACKAGE AND ITS MANUFACTURING METHOD**

(57)Abstract:

PURPOSE: To provide a multi-layer circuit package having an embedded thin-film capacitor.

CONSTITUTION: A circuit package 101 comprises, at least a power core 111a, a ground core 111b, a first signal core 121, a second signal core 131, and an integrally embedded thin-film capacitor 141. The integrally embedded thin-film capacitor works so as to join the first signal core to the second signal core through capacitance. A first signal core structurally comprises at least one first wire 123 terminating at least a first electrode 125, with a second signal core comprising at least a second wire 133 terminating at least a second electrode 135. At least, a part of the first electrode covers a part of the second electrode, while being made away from the second electrode by a thin film 151 of dielectric. The first electrode, the second electrode, and the dielectric thin film define an integrally embedded

